

AON7422L-VB Datasheet N-Channel 30 V (D-S) MOSFET

Top View

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PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω) Typ.	I _D (A)	Q _g (Typ.)		
30	0.004 at V _{GS} = 4.5 V	60	33.5 nC		
50	0.005 at V_{GS} = 2.5 V	50	33.3110		

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g and UIS Tested Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

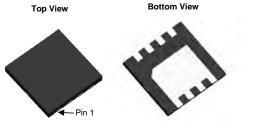
- Motor Control
- Industrial
- Load Switch
- ORing

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DFN 3x3 EP

N-Channel MOSFET ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted) Parameter Symbol Limit Unit Drain-Source Voltage V_{DS} 30 V Gate-Source Voltage V_{GS} ± 20 T_C = 25 °C 60^{a, e} 40^{a, e} T_C = 70 °C Continuous Drain Current (T_J = 150 °C) I_D T_A = 25 °C 22^{b, c} 15^{b, c} T_Δ = 70 °C А Pulsed Drain Current (t = 300 µs) I_{DM} 150 T_C = 25 °C 35 Continuous Source-Drain Diode Current I_S 3.3^{b, c} T_A = 25 °C Single Pulse Avalanche Current I_{AS} 20 L = 0.1 mHSingle Pulse Avalanche Energy E_{AS} mJ 20 T_C = 25 °C 52 T_C = 70 °C 33 P_D W Maximum Power Dissipation T_A = 25 °C 3.7^{b, c} T_A = 70 °C 2.4^{b, c} T_J, T_{stg} - 55 to 150 **Operating Junction and Storage Temperature Range** °C Soldering Recommendations (Peak Temperature) 260

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	24	33	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.9	2.4	0/11

Notes:

a. Based on T_C = 25 °C.
b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under steady state conditions is 90 °C/W.

e. Calculated based on maximum junction temperature. Package limitation current is 80 A.



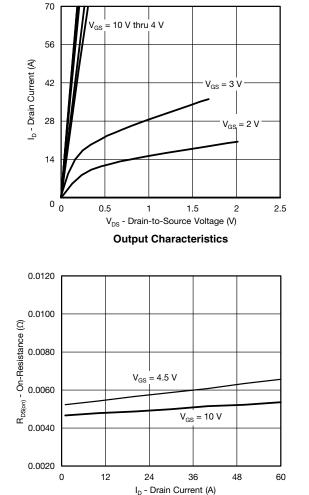
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	o y inis o i			.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	muxi	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30			V	
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J			30		mV/°C	
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA		- 5.6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	0.5		1.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 30 V, V_{GS} = 0 V$			1		
Zero Gate Voltage Drain Current	IDSS	V_{DS} = 30 V, V_{GS} = 0 V, T_{J} = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, $V_{GS} = 10$ V	30			Α	
		V _{GS} = 4.5 V, I _D = 10 A		0.0040		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 7 \text{ A}$		0.0050			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 10 A		65		S	
Dynamic ^b							
Input Capacitance	C _{iss}			6000			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		406		pF	
Reverse Transfer Capacitance	C _{rss}			360			
Tatal Oata Obarra	0	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		68	102		
Total Gate Charge	Q _g			33.5	51		
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 10 A		7.7		- nC	
Gate-Drain Charge	Q _{gd}			13.8			
Gate Resistance	Rg	f = 1 MHz	0.3	0.7	1.4	Ω	
Turn-On Delay Time	t _{d(on)}			24	45		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		24	45		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		32	60		
Fall Time	t _f			12	24	-	
Turn-On Delay Time	t _{d(on)}			14	28	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		13	26	-	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 10 A, V_GEN = 10 V, R_g = 1 Ω		33	60		
Fall Time	t _f			8	16		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	ا _S	$T_{C} = 25 \ ^{\circ}C$		35		Δ	
Pulse Diode Forward Current	I _{SM}			70		A	
Body Diode Voltage	V _{SD}	$I_{S} = 3 \text{ A}, V_{GS} = 0 \text{ V}$		0.7	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			21	40	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		10	20	nC	
Reverse Recovery Fall Time	t _a	$r_F = 10 \text{ A}, \text{ u/ul} = 100 \text{ A/}\mu\text{s}, 1\text{ J} = 25 ^{\circ}\text{C}$		9			
Reverse Recovery Rise Time	t _b	-		12		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

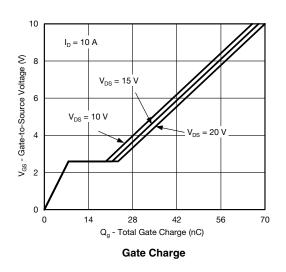
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

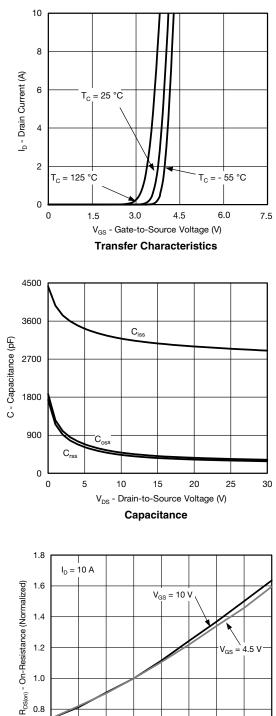




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

On-Resistance vs. Drain Current and Gate Voltage





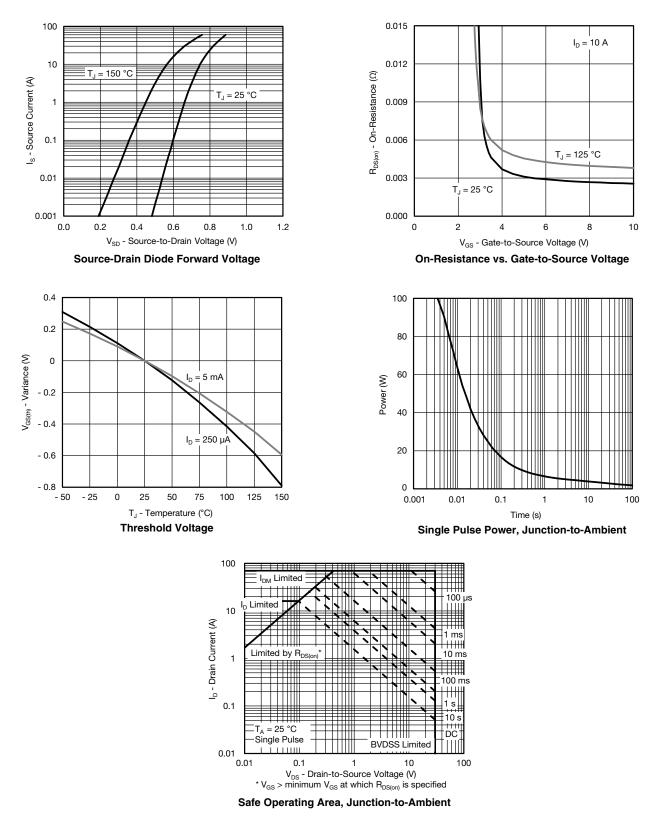


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On-Resistance vs. Junction Temperature

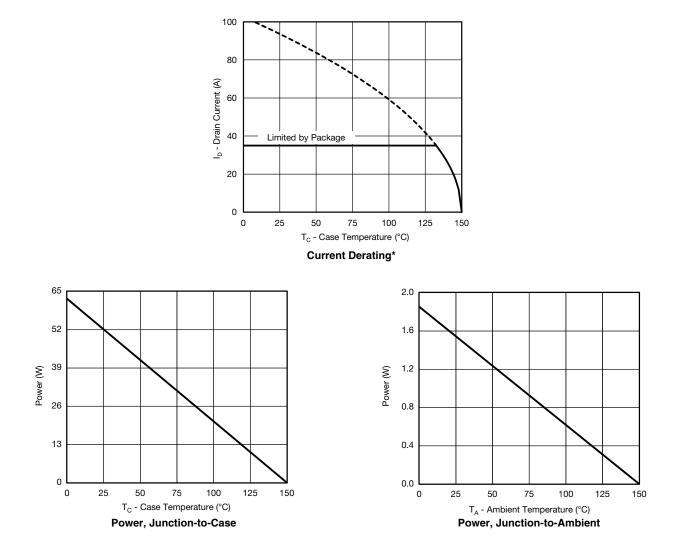








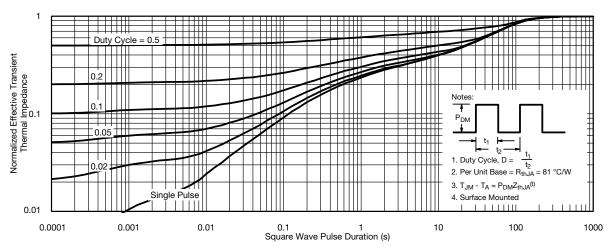
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



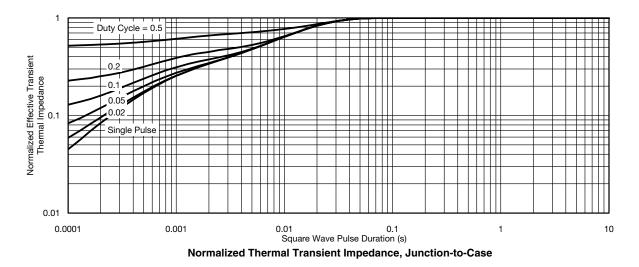
* The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



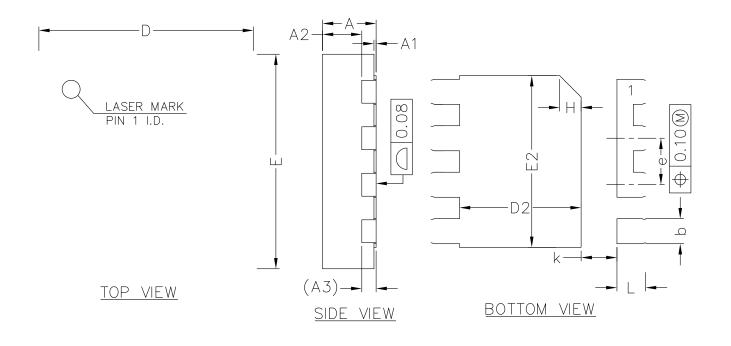
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







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<u>SIDE VIEW</u>

SYMBOL	MIN	NOM	MAX	
А	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
A2	0.50	0.55	0.60	
A3	0.20REF			
b	0.30	0.35	0.40	
D	2.90	3.00	3.10	
E	2.90	3.00	3.10	
D2	1.60	1.70	1.80	
E2	2.30	2.40	2.50	
е	0.55	0.65	0.75	
К	0.40	0.50	0.60	
L	0.35	0.40	0.45	

COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)



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